

Near Memory Computing

Spectral and Sparse Accelerators

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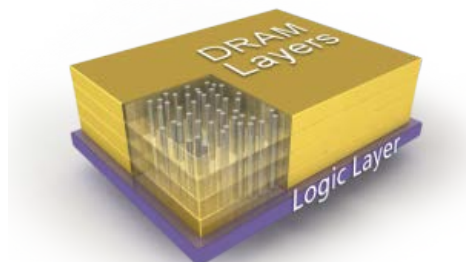
Co-Founder, SpiralGen

www.spiralgen.com

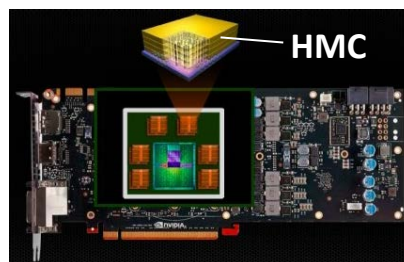
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DRAM-Optimized Near Memory Acceleration

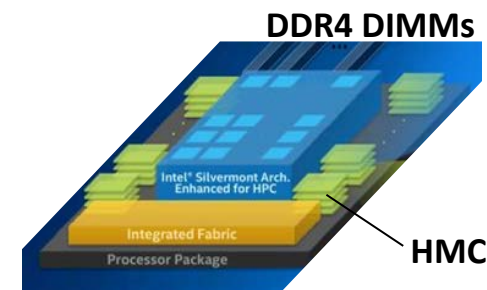
- **Enabling technology: 3D stacked integration**
 - Logic and DRAM layers connected by TSVs
 - Better timing, lower area, advanced IO in the logic layer



Micron HMC



Nvidia Volta



Intel Knights Landing

- **Accelerators in 3D DRAM, behind the conventional interface**
 - Bandwidth and latency concerns still exist to off-chip
 - Integration behind conventional interface opens up internal resources
- **DRAM operation and organization aware accelerators**
 - Conventional near memory computing only aim to reduce the communication distance between memory and processor

Concept: Memory-Side Accelerators

■ Idea: Accelerator on DRAM side

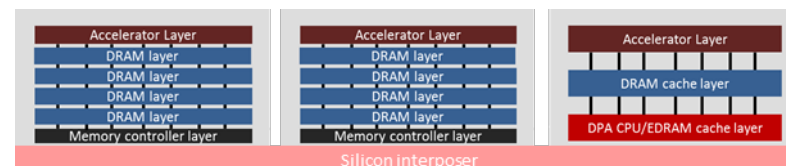
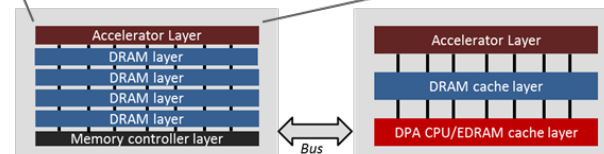
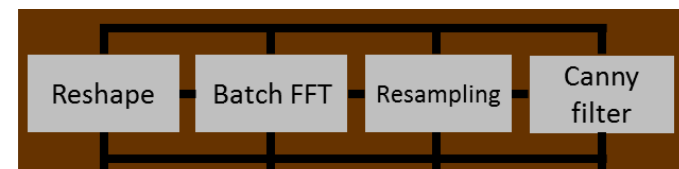
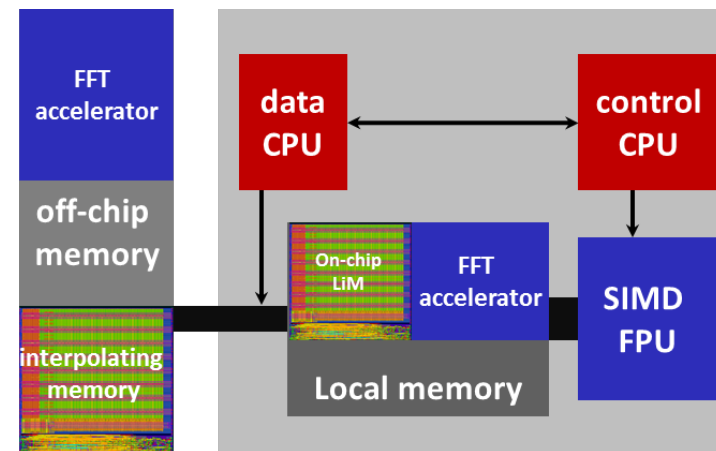
- No off-DIMM data traffic
- Huge problem sizes possible
- 3D stacking is enabling technology

■ Configurable array of accelerators

- Domain specific, highly configurable
- Cover DoD-relevant kernels
- Configurable on-accelerator routing

■ System CPU

- Multicore/manycore CPU
- CPU-side accelerators
- Explicit memory management
- SIMD and multicore parallelism



Silicon interposer

Memory-Side Accelerator Architecture

■ DRAM-side Accelerator

- LiM layer in stacked DRAM
- Array of acceleration engines
- Domain specific, highly configurable

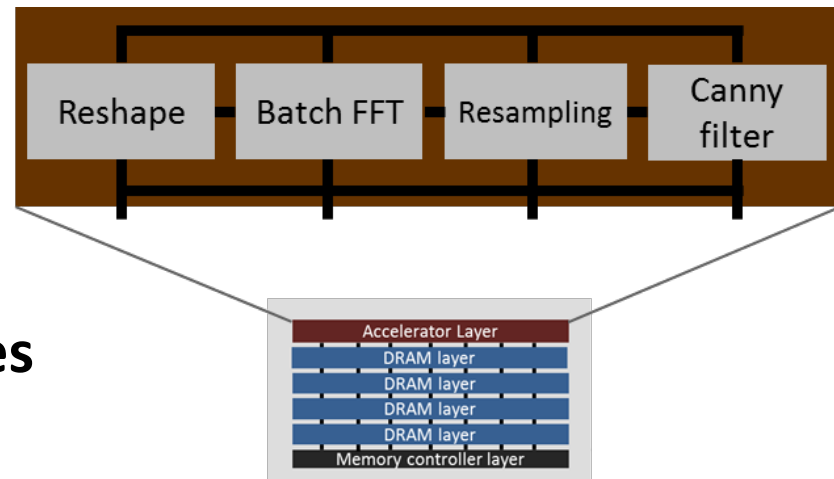
■ Customized Acceleration Pipelines

- DRAM-to-DRAM streaming
- Connect and configure multiple engines
- Configurable on-LiM routing

■ Accelerator Cores

- **Reshape**: linear-to-block data layout changes
- **Batch FFT**: primitive for large 1D and 2D FFTs
- **Resampling**: interpolation, geometric transformations, image alignment
- **Feature extraction**: edge and shape detection

■ Example: PFA SAR requires Reshape, Batch FFT and Resampling



Simulation, Emulation, and Software Stack

■ Accelerator Simulation

- **Timing:** Synopsis DesignWare
- **Power:** DRAMSim2, Cacti, Cacti-3DD
McPAT



■ Full System Evaluation

- Run code on real system (Haswell, Xeon Phi) or in simulator (SimpleScalar,...)
- Normal DRAM access for CPU, but trap accelerator command memory space, invoke simulator

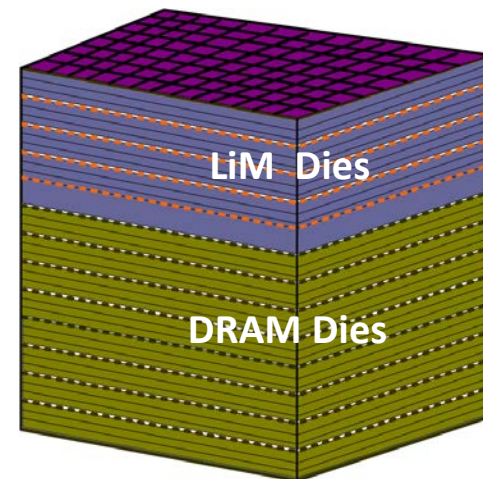
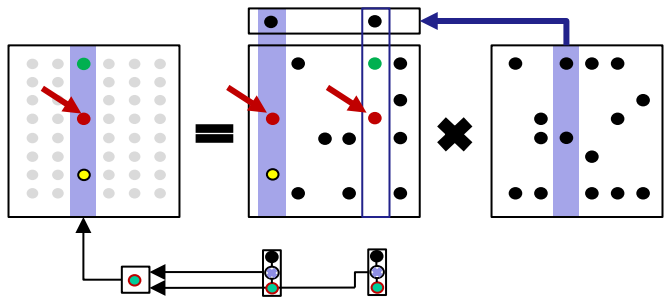
```
#include <accelerator-fft3.h>
...
{
    fftw_complex *in, *out;
    fftw_plan p;
    ...
    in = (fftw_complex*)
        fftw_malloc(sizeof(fftw_complex) * N);
    out = (fftw_complex*)
        fftw_malloc(sizeof(fftw_complex) * N);
    p = fftw_plan_dft_1d(N, in, out,
        FFTW_FORWARD, FFTW_ESTIMATE);
    ...
    fftw_execute(p); /* repeat as needed */
    ...
    fftw_destroy_plan(p);
    fftw_free(in); fftw_free(out);
}
```

■ API and Software stack

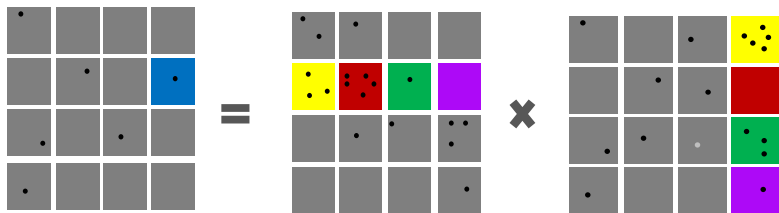
- **Accelerator:** memory mapped device with command and data address space
- **User API:** C configuration library, standard API where applicable
- **Virtual memory:** fixed non-standard logical-to-physical mapping
- **Memory management:** Special `malloc/free`, Linux kernel support

Sparse Matrix Multiplication Accelerator

On-chip: regular SpGEMM kernel



Off-chip: SRUMMA (tiled shared memory algorithm)



Scratchpad: Hierarchical tiling

SRAM

logic-in-memory

$$\begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix} \times \begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix} + \begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix} \times \begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix} = \begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix}$$

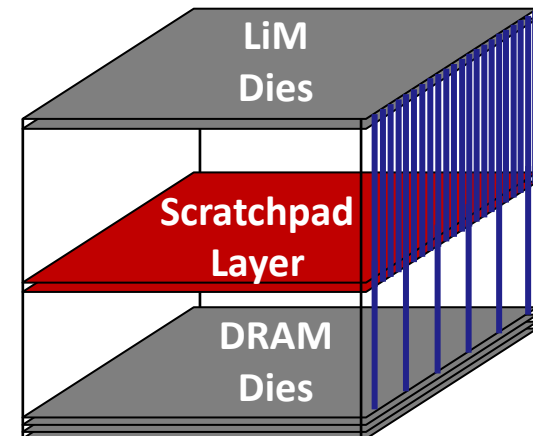
EDRAM

scratchpad

$$\begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix} \times \begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix} = \begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix}$$

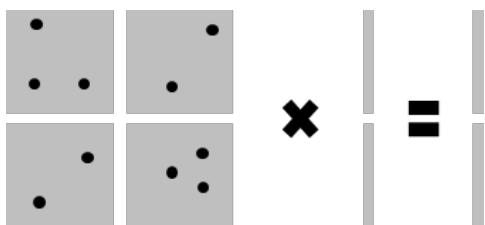
DRAM

$$\begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix} \times \begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix} = \begin{bmatrix} \bullet & \bullet \\ \bullet & \bullet \end{bmatrix}$$



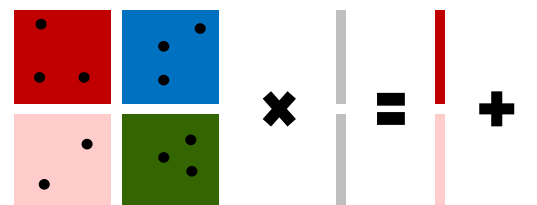
Sparse Matrix-Vector Product Accelerator

SpMV Kernel



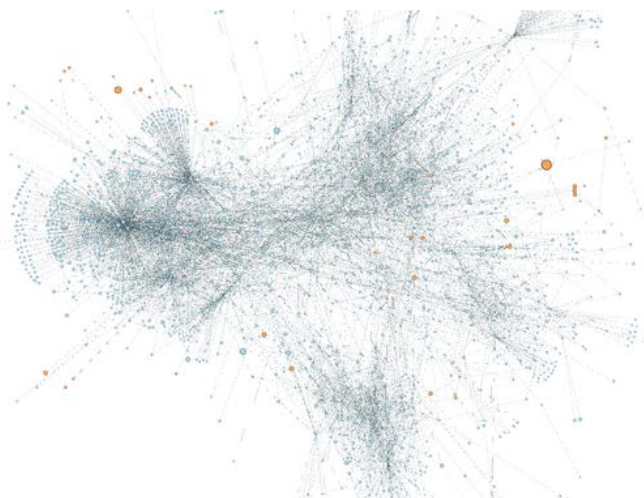
- Standard sparse matrix times dense vector
- Matrix is very sparse (a few non-zeroes per row)
- Matrix and vector size is large (>10M x 10M/GB)

Algorithm

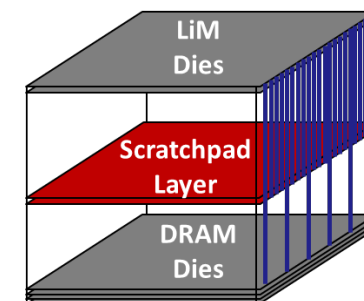
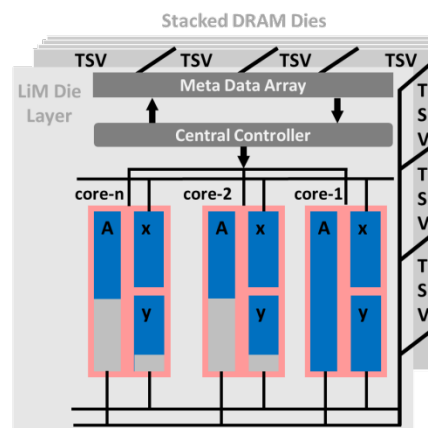


- Block-column multiply + merge step
- Partial results are streamed to DRAM
- Matrix streams from DRAM
- Vector segment is held in scratchpad/EDRAM

Target: Large Sparse Graphs

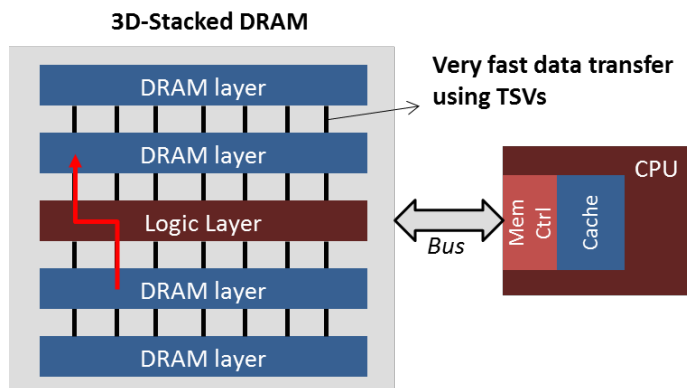


3DIC Memory Side Accelerator

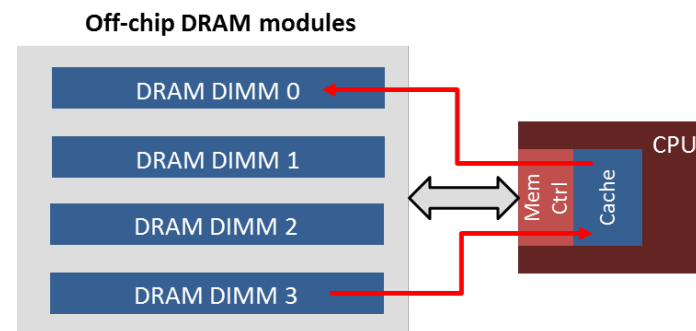


In-DRAM Reshape Accelerator

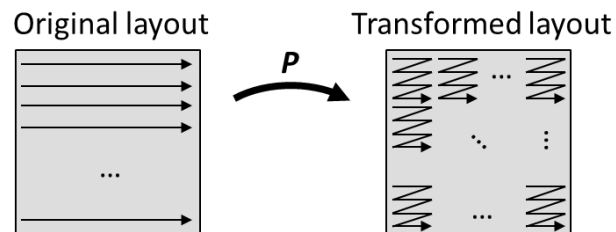
3DIC Reshape Stack



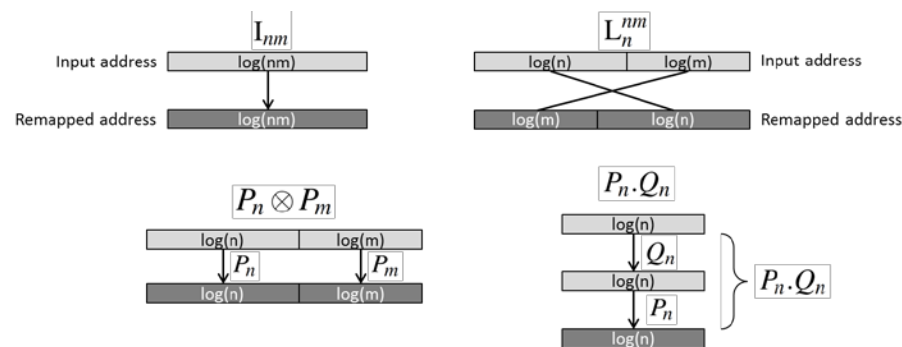
Traditional System



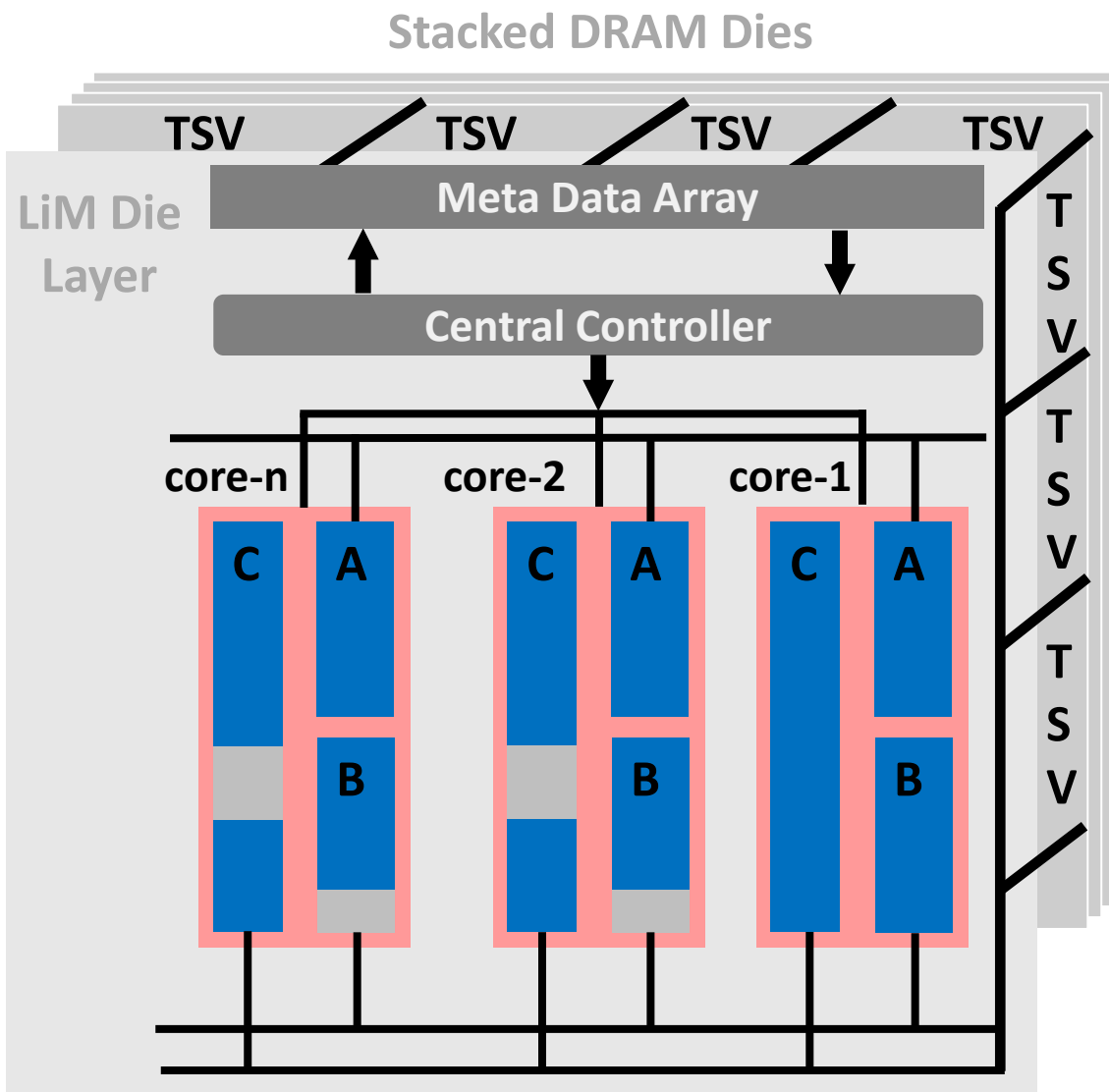
Reshape Operation



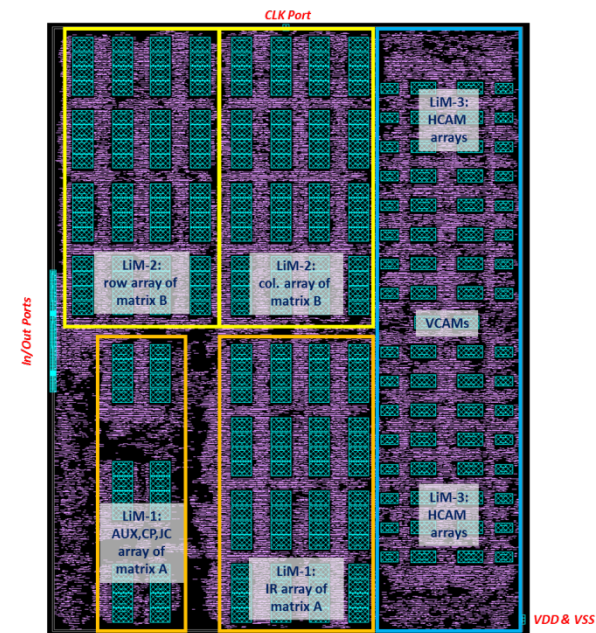
Abstraction: Bit Permutations



3DIC DRAM + SpGEMM Multicore Design



65nm test chip



- Taped out (65nm)
- Core Area: 1.003 x 1.292 mm²
- Transistor count > 1M
- Frequency: 525MHz (SS @ICC)
- Power: 150mW (@DC)

SpGEMM: Experimental Results

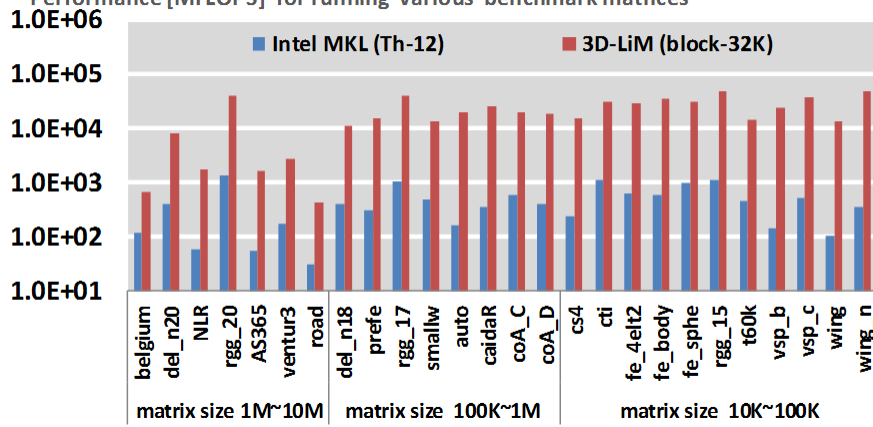
Intel Dual-CPU Intel Xeon E5-2430 system

- about 140W, 6 DRAM channels, 64 GB/s max, 6 DIMMs (48 chips), 210 GFLOPS peak
- Intel MKL 11.0 mkl_dcsrcmultdcsr (unsorted):
100 MFLOPS – 1 GFLOPS, 1 – 10 MFLOPS/W

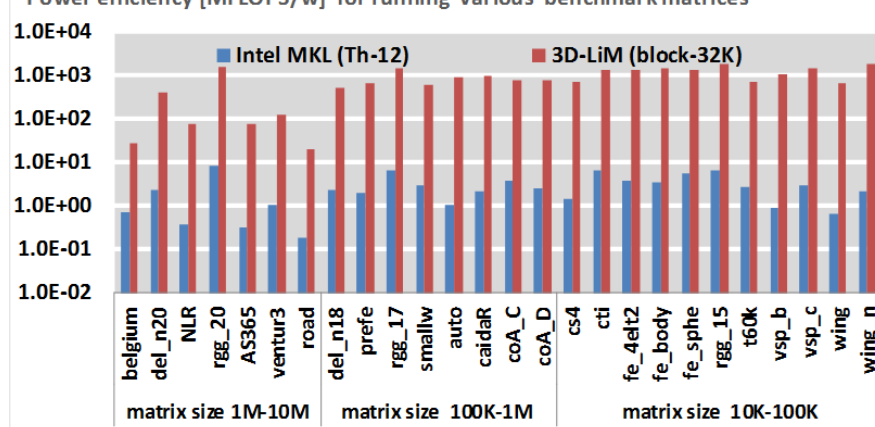
Our 3DIC System

- 4 DRAM layers@ 2GBit, 1 logic layer, 32nm, 30 – 50 cores, 1GHz, 30 – 50 GFLOPS peak
- Performance: **10 – 50 GFLOPS @ 668GB/s with 1024 TSV**
Power efficiency: **1 GFLOPS/W @ 350GB/s with 512TSV or 8GB/s with 1024 TSV**

Performance [MFLOPS] for running various benchmark matrices



Power efficiency [MFLOPS/w] for running various benchmark matrices

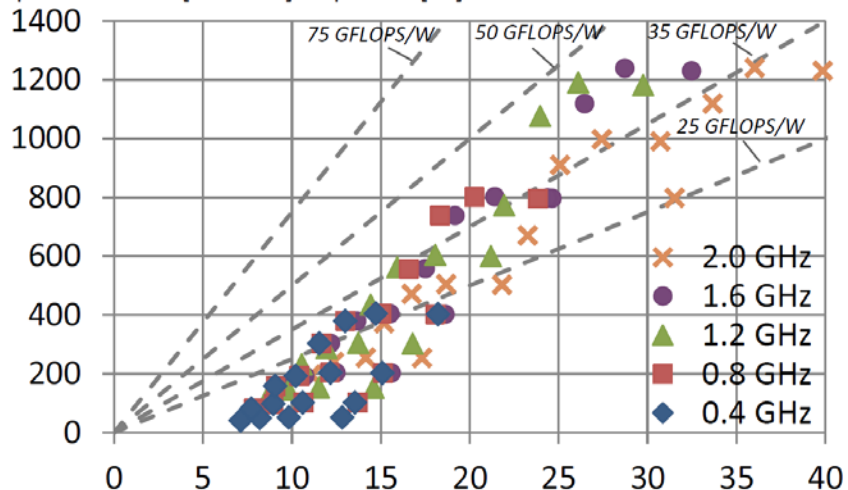


Matrices from University of Florida sparse matrix collection

3DIC for 2DFFT and PFA SAR

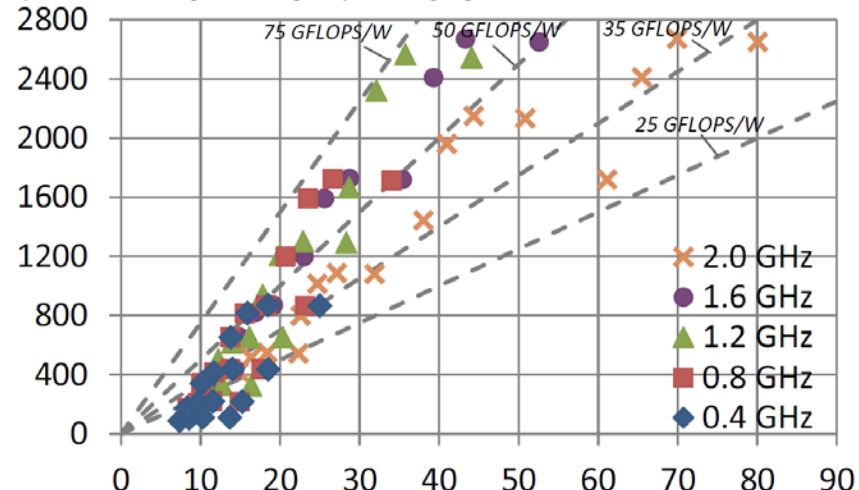
8192x8192 2D-FFT with 3D-stacked DRAM

performance [GFLOPS] vs power [W]



8192x8192 SAR with 3D-stacked DRAM

performance [GFLOPS] vs power [W]



- **3DIC:** 8Gbit, 4-layer DRAM + 1-layer logic, 16 banks/layer, 512 TSV/bank, 1KB pages, 32nm (320GB/s max BW)
- **2DFFT:** tiled FFT, tile size matches DRAM row buffers
- **PFA SAR:** Polar to rectangular local interpolation with logic-in-memory
More flops for the same # of accesses

Results: DRAM-aware FFT Algorithms

DRAM-aware FFT algorithms optimized by SPIRAL

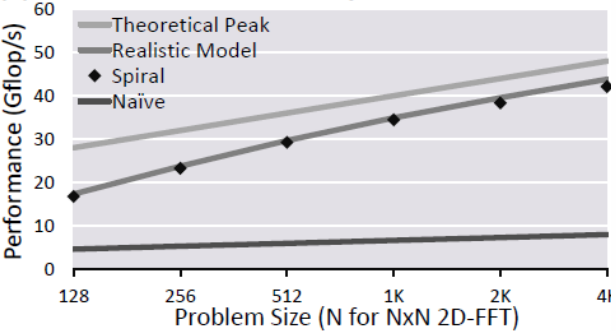
$$\text{DFT}_{n \times n} = \left((R_{t2}^T R_{t3}^T (I_{n/k} \otimes \tilde{I}_k \otimes \text{DFT}_n) R_{t3} R_{t2} \mid R_{t0}^T R_{t1}^T (I_{n/k} \otimes \tilde{I}_k \otimes \text{DFT}_n) R_{t1} R_{t0}) \overline{Q} \right)^{\overline{P}}, \text{ where } P = Q^{-1} = I_{n/k} \otimes L_{n/k}^n \otimes I_k.$$

$$\text{DFT}_{n \times n \times n} = \left(((I_{n^2/k^2} \otimes \tilde{I}_{k^2} \otimes \text{DFT}_n)^{R_{c2}} \mid (I_{n^2/k^2} \otimes \tilde{I}_{k^2} \otimes \text{DFT}_n)^{R_{c1}} \mid (I_{n^2/k^2} \otimes \tilde{I}_{k^2} \otimes \text{DFT}_n)^{R_{c0}}) \overline{Q} \right)^{\overline{P}}, P = Q^{-1} = (I_{n^2/k^2} \otimes L_{n/k}^n \otimes I_{k^2}) (I_{n/k} \otimes L_{n/k}^n \otimes L_{n/k}^n \otimes I_k)$$

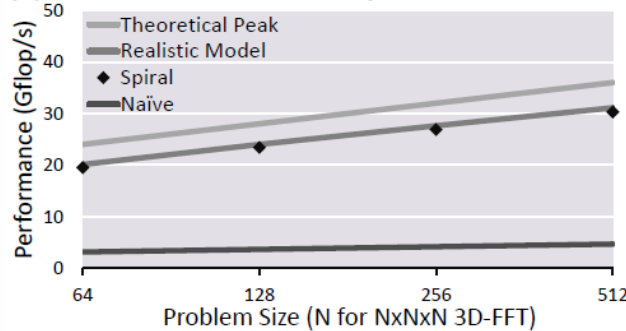
$$\text{DFT}_{n^2} = \left((R_{t2}^T R_{t3}^T (I_{n/k} \otimes \tilde{I}_k \otimes \text{DFT}_n) R_{t3} R_{t2} \mid R_{t0}^T R_{t1}^T D_n^2 (I_{n/k} \otimes \tilde{I}_k \otimes \text{DFT}_n) R_{t3} R_{t2}) \overline{Q} \right)^{\overline{P}}, \text{ where } P = Q^{-1} = I_{n/k} \otimes L_{n/k}^n \otimes I_k.$$

Performance model and power/performance simulation results

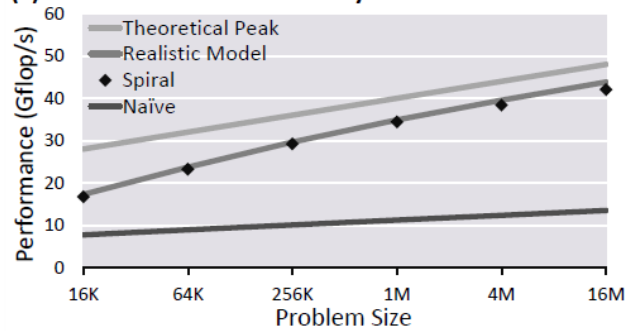
(a) 2D-FFT with Tiled Data Layout



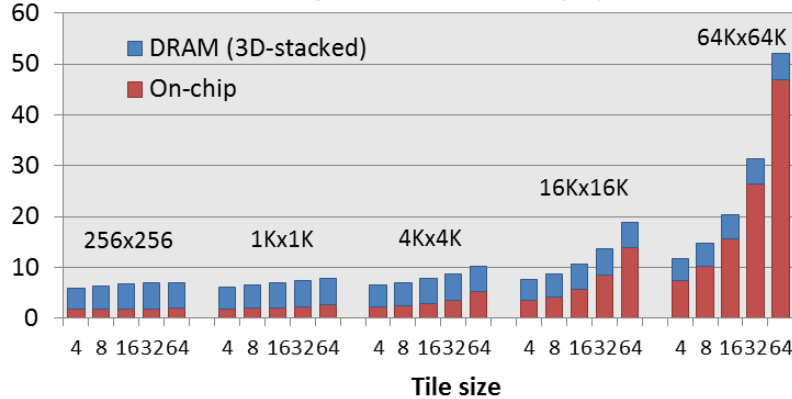
(b) 3D-FFT with Cubic Data Layout



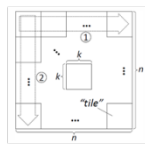
(c) 1D-FFT with Tiled Data Layout



2D-FFT Power Consumption Breakdown (W)



2D tiles



$$A \rightarrow (A \overline{Q})^{\overline{P}}, \text{ where } Q = P^{-1}$$

$$AB \rightarrow A|B$$

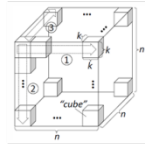
$$I_n \otimes A_n \rightarrow I_n^2 (I_{n/k} \otimes \tilde{I}_k \otimes A_n) I_n^2$$

$$A_n \otimes I_n \rightarrow L_n^2 (I_{n/k} \otimes \tilde{I}_k \otimes A_n) L_n^2$$

$$I_n^2 \rightarrow \underbrace{(I_{n/k} \otimes \tilde{I}_k^2 \otimes I_k)}_{R_{c1}} \underbrace{(I_{n/k} \otimes \tilde{I}_k \otimes L_{n/k}^n \otimes I_k)}_{R_{c0}}$$

$$L_n^2 \rightarrow \underbrace{(I_{n/k} \otimes \tilde{I}_k^2 \otimes I_k)}_{R_{c3}} \underbrace{(L_{n/k}^n \otimes \tilde{I}_k)}_{R_{c2}}$$

3D bricks



$$I_n \otimes I_n \otimes A_n \rightarrow I_n^3 (I_{n^2/k^2} \otimes \tilde{I}_{k^2} \otimes A_n) I_n^3$$

$$I_n \otimes A_n \otimes I_n \rightarrow (I_n \otimes L_n^2) (I_{n^2/k^2} \otimes \tilde{I}_{k^2} \otimes A_n) (I_n \otimes L_n^2)$$

$$A_n \otimes I_n \otimes I_n \rightarrow L_n^3 (I_{n^2/k^2} \otimes \tilde{I}_{k^2} \otimes A_n) L_n^3$$

$$I_n^3 \rightarrow \underbrace{(I_{n^2/k^2} \otimes \tilde{I}_{k^2} \otimes I_k)}_{R_{c1}} \underbrace{(I_{n^2/k^2} \otimes \tilde{I}_{k^2} \otimes L_{n/k}^n \otimes I_k)}_{R_{c0}}$$

$$I_n \otimes L_n^2 \rightarrow \underbrace{(I_{n/k} \otimes \tilde{I}_k^2 \otimes I_{k^2})}_{R_{c3}} \underbrace{(I_{n/k} \otimes \tilde{I}_k \otimes L_{n/k}^n \otimes I_k)}_{R_{c2}}$$

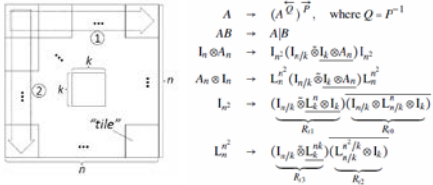
$$L_n^3 \rightarrow \underbrace{(I_{n/k} \otimes \tilde{I}_k^2 \otimes I_{k^2})}_{R_{c3}} \underbrace{(L_{n/k}^n \otimes \tilde{I}_k \otimes I_k)}_{R_{c2}}$$

Near Memory Computing in DARPA PERFECT

HW/SW Formalization

SPIRAL System

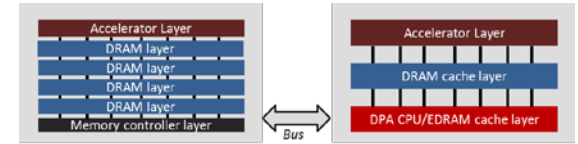
Hardware Synthesis



Algorithm+HW Design

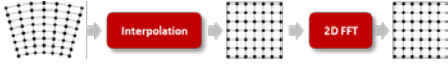
Memory-Side Accelerators

3DIC System



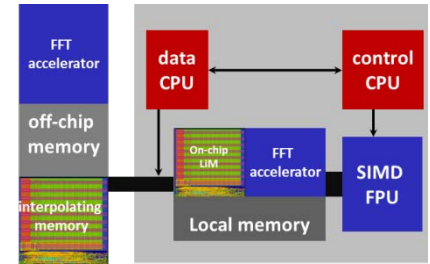
75 GFLOPS/W

Software Synthesis



$SAR_{k \times m \rightarrow n \times n} \rightarrow DFT_{n \times n} \circ Interp_{k \times m \rightarrow n \times n}$
 $DFT_{n \times n} \rightarrow (DFT_n \otimes I_n) \circ (I_n \otimes DFT_n)$
 $Interp_{k \times m \rightarrow n \times n} \rightarrow (Interp_{k \rightarrow n} \otimes I_n) \circ (I_k \otimes Interp_{m \rightarrow n})$
 $Interp_{p \rightarrow s} \rightarrow \left(\bigoplus_{i=0}^{n-2} InterpSeg_k \right) \oplus InterpSegPruned_{k,\ell}$
 $InterpSeg_k \rightarrow G_j^{n-k} \circ iPrunedDFT_{n \rightarrow n} \circ \left(\frac{1}{n} \right) \circ DFT_n$

Accelerator Architecture



Low Power Accelerator Cores

Logic-in-memory for sub-22nm CMOS

Design Tools and Simulation

(a) SAR Polar Reformatting Generator

Parameters:

Data_precision: 32 bits

Division_resolution: 8 bits

Number_of_pulses: 256

Samples_per_pulse: 256

Radius_lower_bound: 488

Radius_upper_bound: 488.33

Angle_width: 0.02

Inter_resolution: 8 bits

Interpolation_order: 8 bits

Submit Changes

(b) Bilinear Interpolation Memory Generator

Parameters:

Data Precision: 32 bits

Data format: Fixed-pt

Data array size (k): 256 W 256

Inter. Resolution (r): 8 bits

Interpolation order(d): Bilinear

Address Partition: Rectangular Access

Smart Memory: Polynomial Interpolation

Submit Changes

(c) Rectangular Access Memory Generator

Parameters:

Data array size x (2^m): 256

Data array size y (2ⁿ): 256

Access rectangular size x (2^m): 2

Access rectangular size y (2ⁿ): 2

Precision (w): 32

Cell size (2^s): 2

X Decoder: Y Decoder

Memory: Brick

Column: Max

Write Driver: WL_And

Submit Changes